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FORM PO-1595 COVER SHEE 10-29-1999 101184181	U.S. Department of Commerce Patents & Trademark Office Attorney Docket No. <u>P806-9003</u> Date: <u>March 15, 1999</u>			
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof				
1. Name of conveying party(ies) Minoru HIRAI; Shigeyuki UEDA; Osamu MIYATA; Tomoharu HORIO Additional name(s) of conveying party(ies) attached? Yes	2. Name and address of receiving party(ies): Name: ROHM CO., LTD. Internal Address: 21, Saiin Mizosaki-cho, Ukyo-ku, Kyoto-shi, Kyoto 615-8585, Japan City:State:Zip: Additional name(s) & address(es) attached? Yes XX No			
A. Patent Application No.(s) New Application Additional numbers attached?Yes XX No 5. Name and address of party to whom correspondence 6. Total number of applications and patents involved:				
concerning document should be mailed: NIKAIDO, MARMELSTEIN, MURRAY & ORAM LLP Internal Address: Street Address: Metropolitan Square, 655 15th St., N.W.,	7. Total fee (37 CFR 3.41)\$ 40.00 XX Included in attached Check #19019 XX Any additional fees are authorized to be			
Suite 330 Street Lobby City: Washington State: DC Zip: 20005-5701	8. Deposit account number: 14-1060 (Attach duplicate copy of this page if paying by deposit account)			
DO NOT USE THIS SPACE				
9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. George E. Oram. Jr. Name of Person Signing Reg. No. 27,931 Total number of pages including cover sheet, attachments and document:				

PATENT REEL: 010335 FRAME: 0724

ATTO	DRNEY	DOCKET	NO.
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ASSIGNMENT

	Serial No	Filed		
	WHEREAS,	Minoru HIRAI, Shigeyuki UEDA, Osamu MIYATA and		
		Tomoharu HORIO		
Insert Name(s) of Inventor(s)				
	(hereinafter designa	ated as the undersigned) has (have) invented certain new and useful improvements		
Insert Title	in PROCESS F	OR MANUFACTURING SEMICONDUCTOR WAFER, PROCESS FOR		
of Invention	MANUFACTURING SEMICONDUCTOR CHIP, AND IC CARD			
	for which an applica	ation for Letters Patent of the United States of America has been executed by the		
Insert Date	undersigned on	March 1, 1999 ; and		
of Signing of Application	WHEREAS, _	ROHM CO., LTD.		
Insert Name of Assignee				
Insert Address of Assignee	of 21, Saiin	Mizosaki-cho, Ukyo-ku, Kyoto-shi, Kyoto 615-8585 Japan		
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its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America and its territories, dependencies and possessions and the entire right, title and interest and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

PATENT REEL: 010335 FRAME: 0725 The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention of the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) the request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Nikaido, Marmelstein, Murray & Oram the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

Date_	March 1, 1999	_, Name of Inventor_	Minoru I-lireio
			(signature) Minoru HIRAI
Date_	March 1, 1999	_, Name of Inventor_	Shigeyuki Jeda
			(signature) Shigeyuki UEDA
Date_	March 1, 1999	_, Name of Inventor_	Osamu migata
			(signature) Osamu MIYATA
Date_	March 1, 1999	_, Name of Inventor_	Tomoharu Horio
			(signature) Tomoharu HORIO
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			(signature)

RECORDED: 03/19/1999

PATENT REEL: 010335 FRAME: 0726